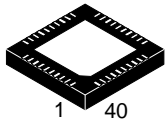


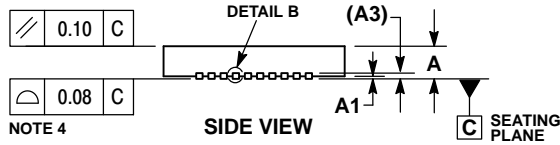
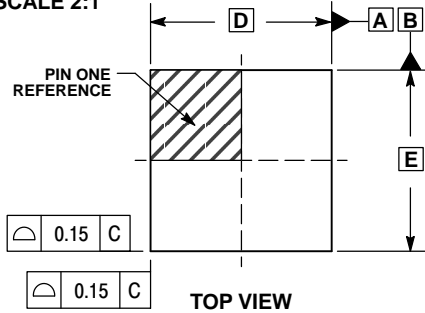
# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

ON Semiconductor®

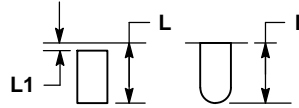


SCALE 2:1

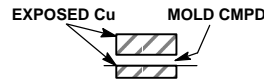


WQFN40 6x6, 0.4P  
CASE 510BK  
ISSUE O

DATE 02 JUL 2014



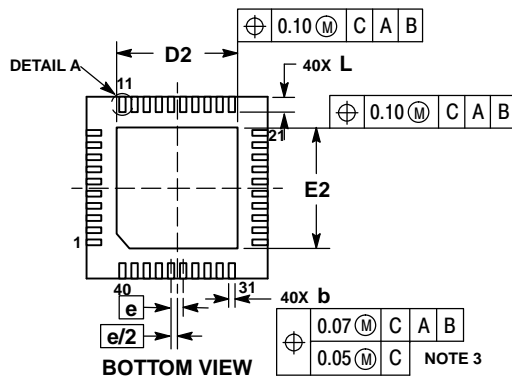
DETAIL A  
ALTERNATE  
CONSTRUCTIONS



DETAIL B  
ALTERNATE  
CONSTRUCTION

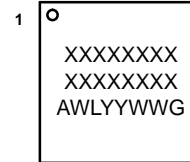
- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
  2. CONTROLLING DIMENSIONS: MILLIMETERS.
  3. DIMENSION *b* APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30mm FROM THE TERMINAL TIP
  4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.70	0.80
A1	---	0.05
A3	0.20	REF
<i>b</i>	0.15	0.25
D	6.00	BSC
D2	3.90	4.10
E	6.00	BSC
E2	3.90	4.10
<i>e</i>	0.40	BSC
L	0.40	0.60
L1	---	0.15



NOTE 3

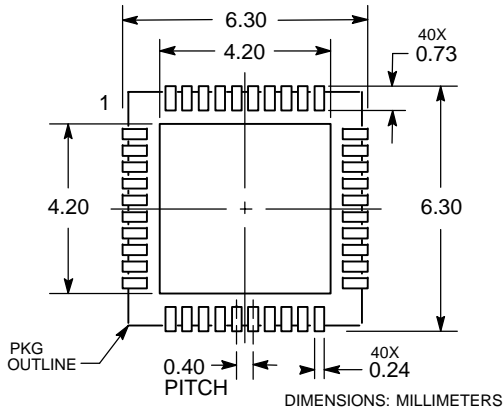
### GENERIC MARKING DIAGRAM\*



- XXXXX = Specific Device Code
- A = Assembly Location
- WL = Wafer Lot
- YY = Year
- WW = Work Week
- G = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

### RECOMMENDED SOLDERING FOOTPRINT



DOCUMENT NUMBER:	98AON87426F	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	WQFN40 6x6, 0.4P	PAGE 1 OF 2

